



New Product Introduction

April 2021

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EasyDUAL™ CoolSiC™ MOSFET power module 1200 V in half-bridge configuration with AlN ceramic

Our new EasyDUAL™ CoolSiC™ MOSFET modules in half-bridge configuration were updated with a new aluminum (AlN) ceramic. This advanced material will support customers in high power density applications like Solar, UPS, traction auxiliary inverters or even ESS and EV Charger.

The newest solutions with AlN ceramic come in half-bridge configuration with 11mOhm $R_{ds(on)}$ in Easy 1B package and 6mOhm $R_{ds(on)}$ in Easy 2B package.

Customers will benefit in different directions from the new high performance ceramic. Most important is the improvement of the $R_{th(jh)}$ by 40%, which will increase the output power or further improve the lifetime.

In addition, these modules are equipped with the best-in-class CoolSiC™ trench MOSFET technology for a superior gate-oxide reliability.



Features

- > Easy 1B, 2B module packages
- > 1200 V CoolSiC™ trench MOSFET
- > Half-bridge configuration
- > High performance aluminum nitride ceramic
- > PressFIT technology

Benefits

- > Easy design-in
- > High degree of freedom for the inverter designer
- > Better thermal conductivity of the DCB material
- > Superior gate-oxide reliability
- > Power density and compact design
- > Minimization of cavity between module and heat sink

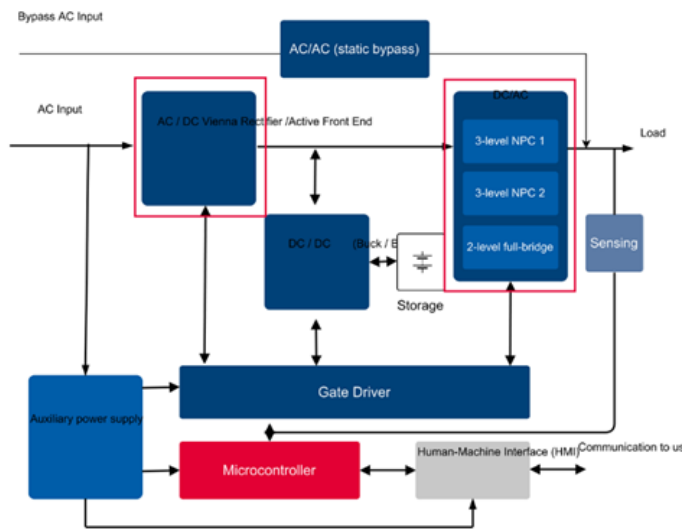
Competitive advantage

- > Superior gate-oxide thickness for highest reliability

Target applications

- > UPS
- > Solar
- > Energy Storage
- > EV Charger
- > Traction auxiliary inverters

System diagram



Product overview incl. data sheet link

OPN	SP Number	Package
FF6MR12W2M1B70BPSA1	SP004486482	AG-EASY2B-2
FF11MR12W1M1B70BPSA1	SP004486464	AG-EASY1B-2

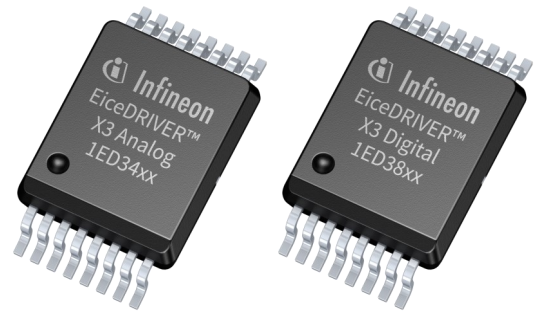
Product collaterals / Online support

- [Product page, FF6MR12W2M1_B70](#)
- [Product page, FF1MR12W1M1_B70](#)
- [Application note](#)

EiceDRIVER™ X3 Analog & Digital with reinforced isolation

This release of X3 Analog (1ED34xx) & X3 Digital (1ED38xx) adds products with reinforced isolation according to VDE 0884-11 to the existing highly flexible, single-channel, isolated gate driver family with DESAT, Miller clamp, soft-off and I2C configurability.

The gate driver family provides typical peak output currents of 3 A, 6 A and 9 A, high precision DESAT function for IGBTs and SiC MOSFETs; many of those features configurable. This enables innovative use cases, such as predictive maintenance.



Features

- > Reinforced isolation according to VDE 0884-11
- > For IGBTs (incl. IGBT7), SiC and Si MOSFETs
- > $\pm 3/6/9$ A typical sinking and sourcing peak output current
- > Precise V_{CEsat} detection (DESAT) with fault output
- > 40 V absolute maximum output supply voltage
- > Flexibility based on feature configuration

Benefits

- > Enables fast design cycles due to low external component count and still offers adjustable DESAT with soft-off functionality
- > Perfect fit for all applications requiring a reliable DESAT protection (including SiC MOSFET & IGBT7),
- > VDE 0884-11 with $V_{ORM} = 1767$ V (peak, reinforced) and UL 1577 (pending) $V_{ISO} = 6$ kV (rms) for 1 s, 5.7 kV (rms) for 1 min
- > Superior application safety based on VDE 0884-11 and UL 1577

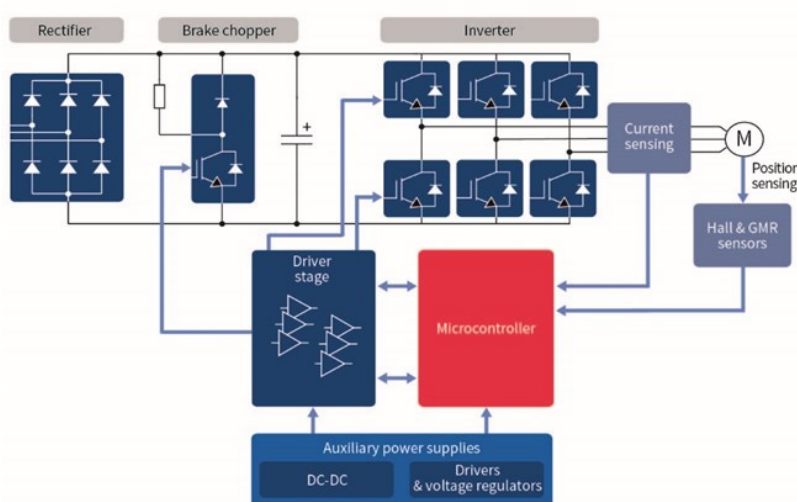
Competitive advantage

- > Enables fast design cycles due to its configurability & low external component count while still offering adjustable DESAT with soft-off functionality (1ED34XX)
- > Unique configurability via I2C for DESAT, soft-off, UVLO, active Miller clamp, over temperature shutdown, two level turn off, highly flexible for customer designs (1ED38XX)

Target applications

- > Industrial motor drives - compact, standard, premium, servo drives
- > Solar inverters
- > UPS systems
- > EV charging
- > Energy storage systems

System diagram



Product collaterals / Online support

[Product family page](#)

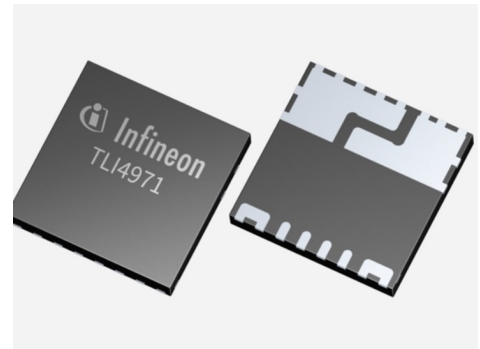
[Application note](#)

Product overview incl. data sheet link

OPN	SP Number	Package
1ED3431MC12MXUMA1	SP003244286	PG-DSO-16
1ED3461MC12MXUMA1	SP003244290	PG-DSO-16
1ED3491MC12MXUMA1	SP003244294	PG-DSO-16
1ED3830MC12MXUMA1	SP001338512	PG-DSO-16
1ED3860MC12MXUMA1	SP001338514	PG-DSO-16
1ED3890MC12MXUMA1	SP001338516	PG-DSO-16
EVAL1ED3491MX12MTOBO1	SP005411273	Board

XENSIV™ – TLI4971 high precision coreless current sensors

We expanded our highly precise current sensor family by six more pre-programmed derivatives for even more applications such as industrial drives-electric drives up to 30 kW-, PV inverters and charging. Highest flexibility is offered by individually programmable parameters, such as current range, overcurrent threshold or output mode. Our sensors offer an accurate and stable current measurement – provided as an analog output voltage. Based on our market-proven temperature and stress compensation, the sensitivity error is as low as 2 % at room temperature. It can be reduced below 2 % with a single point in-system calibration. On top differential measurement with two Hall cells ensures high accuracy even in a noisy environment with cross-talk from adjacent current lines or magnetic stray fields.



Features

- > Three measurement ranges up to 25Apeak, 50Apeak, 75Apeak @ 690VRMS
- > Full scale measurement range $\pm 25\text{A}$, $\pm 50\text{A}$ and $\pm 75\text{A}$
- > AC and DC measurement possible
- > Typical error at 25°C <2%
- > Resistance of the current-rail 225 $\mu\Omega$ typical
- > Analog output signal with 120kHz bandwidth
- > Two separate outputs for overcurrent detection (OCD) feature
- > Programmable overcurrent detection threshold up to 2 times of the measurement range
- > Fast response time for overcurrent detection (typ. <1 μs)
- > Small TISON-8 package (8x8x1mm)
- > Version with UL certification available

Competitive advantage

- > Very low sensitivity error over temperature (<2.5%) and lifetime (<3%)
- > Best in class power dissipation for high currents
- > Programmability of current ranges to enable platform design
- > No shielding against cross-talk required
- > Separate path for overcurrent detection to support OC pre-warning and shut-down
- > Limited number of external components due to integrated overcurrent detection

Benefits

- > Ultra-low power loss due to low resistance of current rail saves cooling structure
- > Reliable current measurement over lifetime (no re-calibration)
- > Functional isolation for high voltage applications
- > Integrated overcurrent detection safes external circuitry
- > Two overcurrent pins with two independent overcurrent thresholds to define pre-warning and shut-off current
- > Programmable sensor to cover multiple frame sizes for drives

Target applications

- > Electric drives up to 690VRMS
- > Photovoltaic inverters
- > Power supplies
- > Overload or overcurrent detection in high voltage power circuits
- > Current sensor applications requiring UL certificate

Product overview incl. data sheet link

OPN	SP Number	Package
TLI4971A025T5E0001XUMA1	SP005446644	PG-TISON-8
TLI4971A025T5UE0001XUMA1	SP005446646	PG-TISON-8
TLI4971A050T5E0001XUMA1	SP005446648	PG-TISON-8
TLI4971A050T5UE0001XUMA1	SP005446651	PG-TISON-8
TLI4971A075T5E0001XUMA1	SP005446653	PG-TISON-8
TLI4971A075T5UE0001XUMA1	SP005446655	PG-TISON-8
TLI4971MS2GOTOBO1	SP005345474	Board
S2GOCURSENSETLI4971TOBO1	SP005345472	Board

Product collaterals / Online support

[Product family page](#)

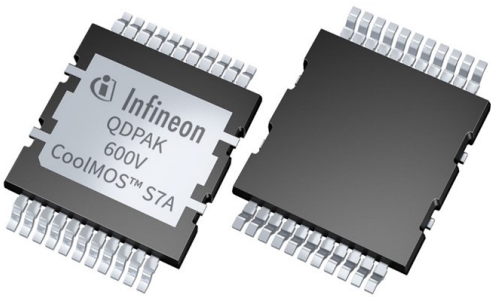
[Application note](#)

[Customer connector](#)

[Product presentation](#)

600 V CoolMOS™ S7A - soft-switching automotive applications

The automotive grade 600 V CoolMOS™ S7A superjunction MOSFET addresses xEV applications where MOSFETs are switched at low frequency, such as HV eFuse, HV eDisconnect and on-board charger in the slow-switching leg of the PFC stage. The innovative package concept offered by the QDPAK top-side cooled (TSC) combined with superior robustness and performance of the CoolMOS™ S7A MOSFET meet the stringent requirements for increased power density, safety, and reliability in these applications. The new MOSFET design offers a cost-optimized, distinctively low on-resistance $R_{DS(on)}$ of 10 mOhm, enabling increased power density and minimized conduction losses, while meeting the highest automotive quality going well beyond the AEC-Q101 standard.



The top-side cooled QDPAK package offers increased efficiency and controllability thanks to its intrinsic kelvin source, high power dissipation capability and innovative cooling concept.

Features

- > Lowest $R_{DS(on)}$
- > Compact top-side-cooled QDPAK package
- > Optimized for conduction performance
- > Improved thermal resistance
- > High pulse current capability
- > Kelvin-source pin improves switching performance at high current

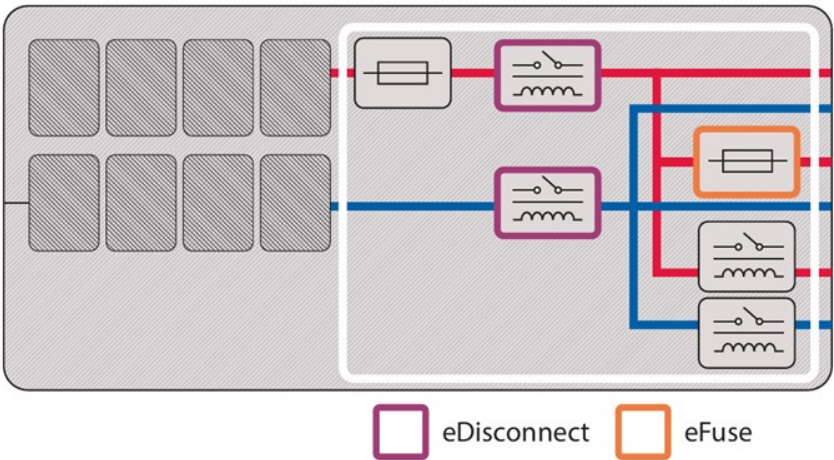
Benefits

- > Minimizes conduction losses
- > Increases energy efficiency
- > More compact and easier designs
- > Lower TCO cost or BOM cost

Target applications

- > HV eFuse
- > HV eDisconnect
- > On-board charger

System diagram



Product collaterals / Online support

[Product page](#)

[Product brief](#)

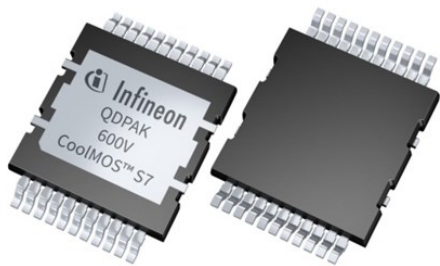
Product overview incl. data sheet link

OPN	SP Number	Package
IPDQ60R010S7AXTMA1	SP002063384	PG-HDSOP-22

600 V CoolMOS™ S7 - soft-switching industrial applications

The IPDQ60R010S7 is Infineon’s lowest $R_{DS(on)}$ 600 V SJ MOSFET in the novel top-side-cooled QDPAK package, ideal for low-frequency switching applications and solid-state solutions.

The 600V CoolMOS™ S7 SJ MOSFET family is optimized for low conduction losses and features the lowest $R_{DS(on)}$ in the market when it comes to high-voltage SJ MOSFETs. It comes with an unprecedented $R_{DS(on)} \times \text{price}$ figure of merit and is a perfect fit for solid-state circuit breakers and relays, PLCs, battery protection, and active bridge rectification in high-power power supplies.



Features

- > Lowest $R_{DS(on)}$
- > Compact top-side-cooled QDPAK package
- > Optimized for conduction performance
- > Improved thermal resistance
- > High pulse current capability
- > Kelvin-source pin improves switching performance at high current

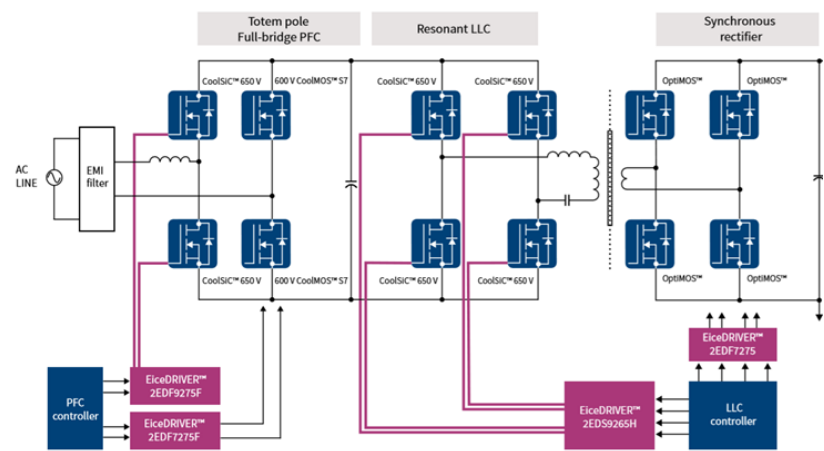
Benefits

- > Minimizes conduction losses
- > Increases energy efficiency
- > More compact and easier designs
- > Eliminates or reduces heat sinks in solid-state design
- > Lower TCO cost or BOM cost

Target applications

- > Solar
- > SMPS
- > UPS
- > PLC
- > LSEV

Block diagram



Product collaterals / Online support

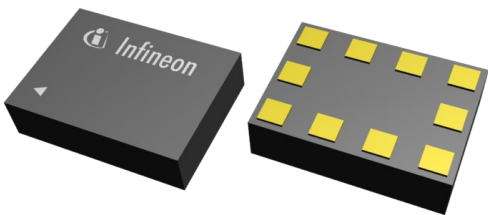
- [Product page](#)
- [Product brief](#)
- [Application note](#)

Product overview incl. data sheet link

OPN	SP Number	Package
IPDQ60R010S7XTMA1	SP003330416	PG-HDSOP-22

BGSC2341ML10 - RF digitally tunable capacitor + SPDT switch

BGSC2341ML10 is a versatile Integrated Circuit (IC) ideal for RF tuning applications such as tunable impedance matching, antenna tuning and tunable filtering. This IC integrates an 8-states tunable capacitor and an extremely low R_{ON} Single Pole Double Throw (SPDT) RF switch function; both controlled by on-chip MIPI 2.1 RFFE digital interface.



Features

- > Designed for high-linearity applications
- > Ultra low R_{ON} resistance of $0.87\ \Omega$ at each SPDT throw in ON state
- > High operating RF Voltage handling 39 V
- > 0.26-2.00 pF tuning range at 1.8 GHz
- > Operating frequencies: 0.4 - 3.8 GHz
- > High ESD robustness
- > MIPI 2.1 RFFE compliant control interface
- > 2 default USID selectable via USID_SEL pin
- > Supply voltage range: 1.65 to 1.95 V
- > Small form factor 1.1 mm x 1.5 mm (MSL1, 260° C per JEDEC J-STD-020)
- > RoHS and WEEE compliant package

Benefits

- > Ultra low R_{ON} SPDT RF switch à Low RF losses in low Z system
- > Extremely low Cmin and 8:1 capacitance tuning range (8 steps)
- > Highly versatile usage

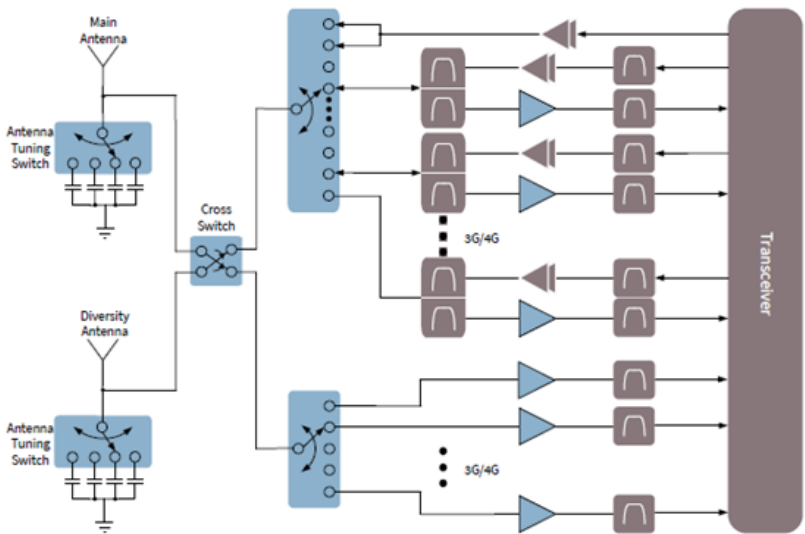
Competitive advantage

- > 8 bits C-tuner for high resolution antenna fine-tuning
- > PCB space saving via SPDT + RF C-tuner SoC integration into a very small 1.1x1.5mm package

Target applications

- > All battery powered cellular applications

System diagram: RF front end in mobile phones



Product collaterals / Online support

[Product page](#)

Product overview incl. data sheet link

OPN	SP Number	Package
BGSC2341ML10E6327XTSA1	SP003086540	PG-TSLP-10

Reverse Conducting R6 IGBT 650 V

Reverse Conducting R6 IGBT 650 V portfolio with its monolithically integrated diode offer the lowest V_{cesat} , lowest power losses and improved diode performances bringing the perfect trade-off between power losses and EMI behavior for all soft switching applications using half-bridge topology

The R6 IGBT family is specifically designed for induction heating application, in order to meet the specific requirements in term of efficiency (lowest possible losses in soft switching conditions), higher output power (optimal thermal behavior), reliability (standard Infineon quality level) and capacity (new 12" production line)



Features

- > Improved IGBT performance to offer best trade-off between power losses and EMI performance
- > Improved diode performance reducing V_f and dependency of gate voltage
- > Diode forward recovery peak and time comparable to co-packed device
- > Portfolio of 30 A, 40 A, and 50 A devices
- > $T_j(max) = 175^{\circ}C$
- > 650 V blocking voltage
- > TO247-3pin package

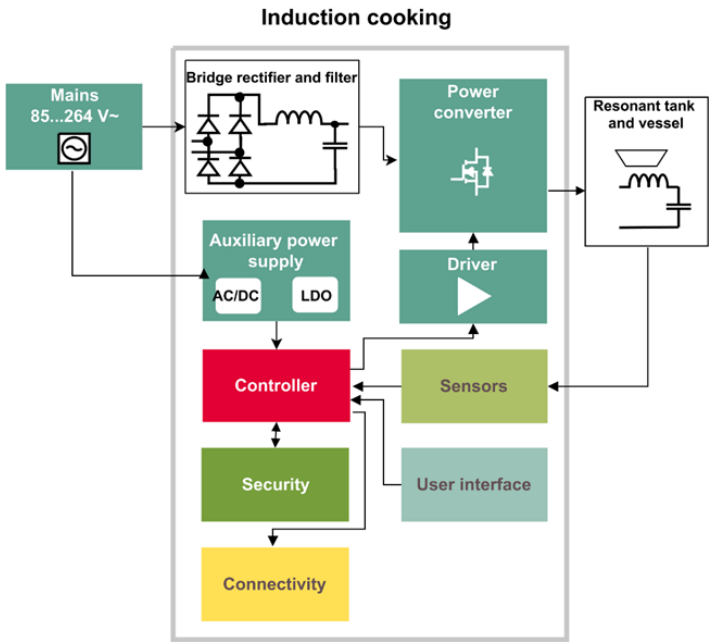
Benefits

- > High compatibility with existing gate driver solutions
- > Optimized performance in application conditions
- > Low conduction losses
- > Low switching losses
- > Improved EMI performance

Target applications

- > Induction cooking
- > Microwave ovens

System diagram



Competitive advantage

- > Reverse Conducting R6 IGBT 650 V represents the optimal choice for half-bridge resonant topology with the best trade-off between power losses and EMI performance

Product collaterals / Online support

[Product family page](#)

Product overview incl. data sheet link

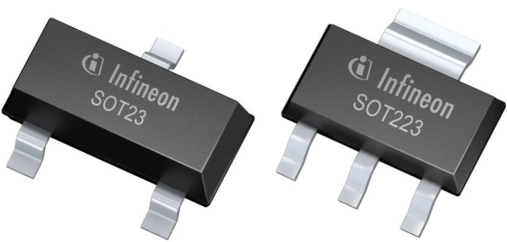
OPN	SP Number	Package
IHW30N65R6XKSA1	SP005399486	PG-TO247-3
IHW40N65R6XKSA1	SP005399488	PG-TO247-3
IHW50N65R6XKSA1	SP005399490	PG-TO247-3

Small Signal/Small Power MOSFETs for the industrial market

Infineon offers high-performance products with the best price/performance ratio in the industry by using cost effective packages combined with leading, reliable and proven silicon technology.

The Small Signal/ Small Power N-channel MOSFETs simplify the design complexity for various of applications in the consumer industry market. The products are available in logic and normal level gate drive capability and feature a wide range of $R_{DS(on)}$ options.

The new products are good alternatives or replacements to existing N-channel products and enable designers to improve performance while reducing the overall bill of materials.



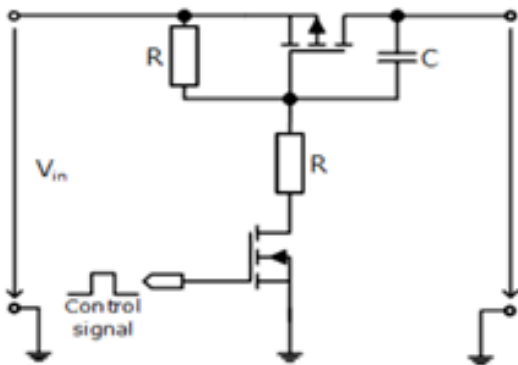
Features

- > Small outline packages
- > Normal and logic level gate drive availability
- > Enhancement and depletion mode N-channel options
- > RoHS compliant and halogen-free
- > Fast switching
- > Avalanche rated
- > Qualified according to JEDEC for Industrial applications

Benefits

- > PCB space and cost savings
- > Best price/performance ratio
- > Gate drive flexibility
- > Reduced design complexity
- > Environmentally friendly
- > High overall efficiency
- > Enables robust design
- > Industry standard qualification level

Block diagram



Target applications

- > Battery management
- > Industrial Drives
- > LED backlighting
- > Load switches
- > Consumer
- > Mutlisource

Product overview incl. product page link

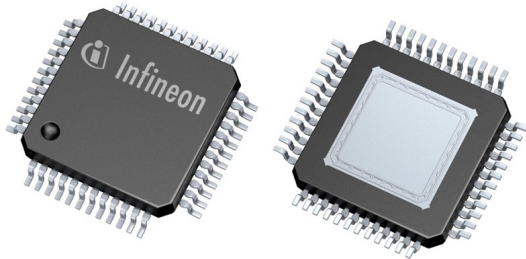
OPN	SP Number	Package
BSS138IXTSA1	SP005558681	PG-SOT23-3
SN7002IXTSA1	SP005558643	PG-SOT23-3
BSS123IXTSA1	SP005558639	PG-SOT23-3
BSS169IXTSA1	SP005558635	PG-SOT23-3
BSS139IXTSA1	SP005558631	PG-SOT23-3
BSS127IXTSA1	SP005558627	PG-SOT23-3
BSP135IXTSA1	SP005558623	PG-SOT223-4

Product collaterals / Online support

- [Product family page](#)
- [Product brief](#)

TLE9241QU - Transmission IO IC

The TLE9241QU is an integrated circuit (IC) for use in automatic transmission control modules. Two gate drive outputs are included for controlling a reverse polarity protected high-side switch typically used to switch off power to the control module while the module is in a sleep state. Two high-side gate drive channels are also included for controlling two “safety” switches. These switches are typically used to provide power to the transmission solenoids. The device also provides interfaces for eight two-wire Hall Effect sensors, four of which can be used with position sensors and four which can be used with either position or speed sensors



Features

- > Four input interfaces for two wire Hall Effect position sensors
 - Short to supply protection
 - Overtemperature protection
 - Sensor state status available by SPI
- > Four input interfaces for two-wire Hall Effect speed sensors
 - Digital output for speed and direction sensing
 - Further features set see position sensors above
- > Two high-side gate drive channels
 - Short circuit protection
 - Programmable overcurrent threshold
 - Output state status available by SPI
- > A high-side gate drive channel for driving n-channel MOSFETs in anti-serial configuration
 - Reverse polarity protected power switch
- > Integrated charge pump
- > 16 bit SPI interface
- > Green Product (RoHS-compliant)

Target applications

- > Automatic Transmission Control Modules
- > Powertrain Control Modules

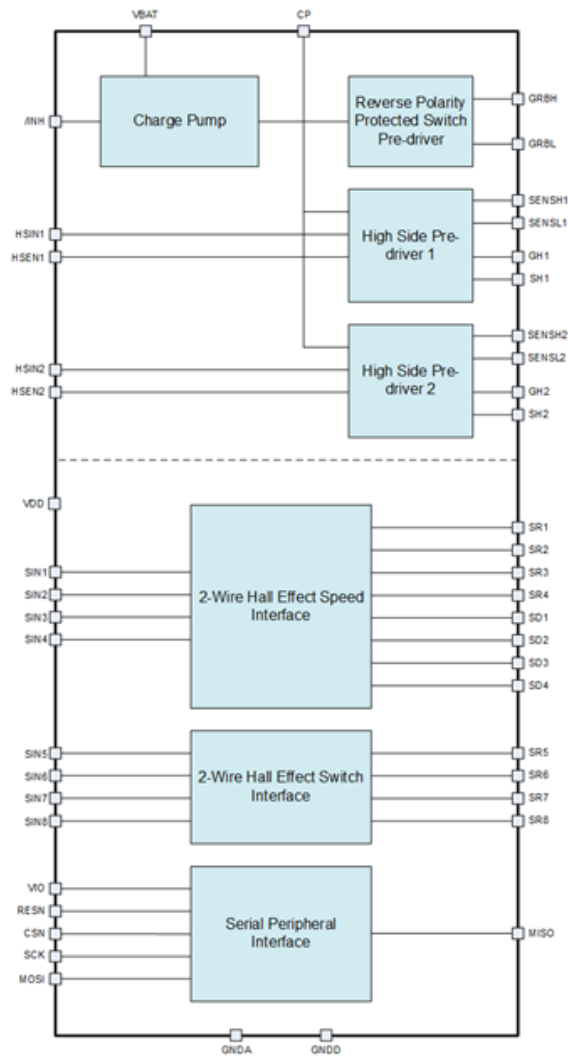
Product collaterals / Online support

[Product page](#)
[User manual](#)

Benefits

- > Compared to a discrete circuit solution
 - ~40% less PCB area
 - ~65% fewer components

Block diagram



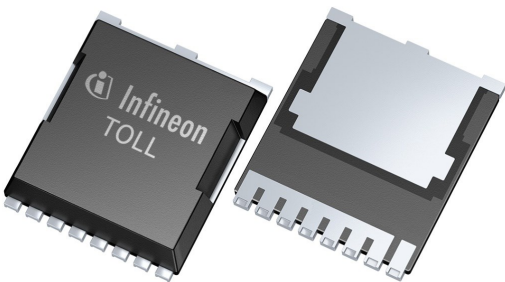
Product overview incl. product page link

OPN	SP Number	Package
TLE9241QUXUMA1	SP001593436	PG-TQFP-48

OptiMOS™5 power MOSFET 80 V in TO-Leadless (TOLL) package

Infineon’s new best-in-class OptiMOS™5 power MOSFET 80V in TOLL (IPT010N08NM5) offers low on-state resistance $R_{DS(on)}$ at 25°C and 175°C. The OptiMOS™ 5 silicon technology is Infineon’s latest generation of power MOSFETs and is especially designed for Synchronous Rectification for Telecom and Server Power Supplies. Combined with the TOLL package, IPT010N08NM5 is targeted for high current applications (up to 425 A), such as Low voltage drives and Battery management system (BMS) inside forklifts, light electric vehicles (LEV), e-bikes, drones, etc.

With 60% space reduction compared to D²PAK 7-pin package, TOLL is the perfect solution where the highest efficiency, outstanding EMI behavior, best thermal performance and space reduction are required.



Features

- > Very low $R_{DS(on)}$ at 25°C and 175°C
- > Low gate charge (Q_g) and output capacitance
- > High-current rating
- > Optimized for synchronous rectification
- > Ideal for high-frequency switching

Benefits

- > Increased power density
- > Low voltage overshoot
- > Less paralleling required
- > Highest system efficiency
- > Reduced switching and conduction losses

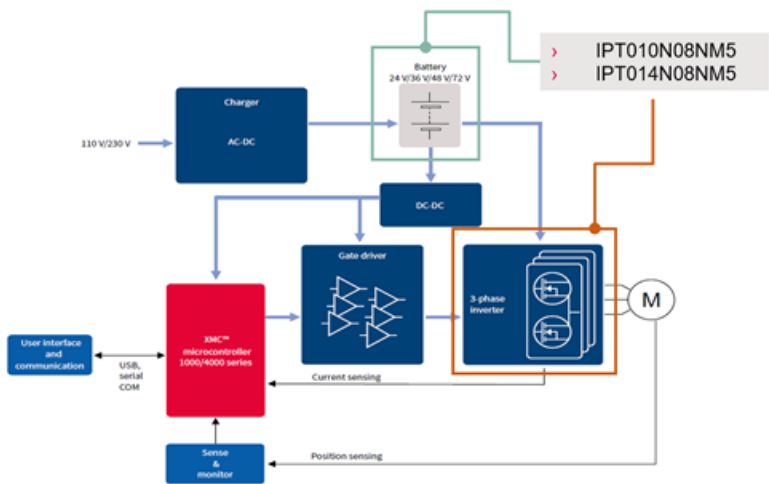
Competitive advantage

- > Low $R_{DS(on)}$ at 25°C and 175°C

Target applications

- > Telecom
- > Server
- > Low voltage drives
- > Light electric vehicles
- > Battery management (BMS)

Block diagram



Product collaterals / Online support

[Product page](#)

Product overview incl. product page link

OPN	SP Number	Package
IPT010N08NM5ATMA1	SP005560711	TOLL

DEMO Distance2GoL

XENSIV™ 24GHz demo platform for the BGT24LTR11

The Distance2GoL radar system is a demo platform for Infineon's 24GHz BGT24LTR11 radar transceiver. The Distance2GoL consists of two boards – the microcontroller board with the XMC4700 (RADAR BB XMC4700) and a radar frontend board (BGT24LTR11 Shield), which features a 4x1 array antenna for the transmitter and receiver sections. It is shielded with a metal cover and absorber material to get the best RF performance.



Features

- > The Distance2GoL combines the BGT24LTR11 RF transceiver with the XMC4700 32-bit ARM® Cortex® M4 MCU.
- > User configurable detection range up to 15 m for human target
- > Detects distance and velocity of closest human or moving target
- > Low power consumption due to duty cycling options
- > Small form factor (4.5 x 3.6 cm)
- > Micro-strip patch antennas with 10 dBi gain and 29°/80° field of view

Benefits

- > Software-controlled FMCW for power saving, reduced costs and less PCB space
- > Smart algorithm enables reliable one-dimensional tracking
- > Operates in harsh environments and detects through non-metallic materials
- > FCC & ETSI compliant
- > Compatible with Arduino for ease of use and fast prototyping

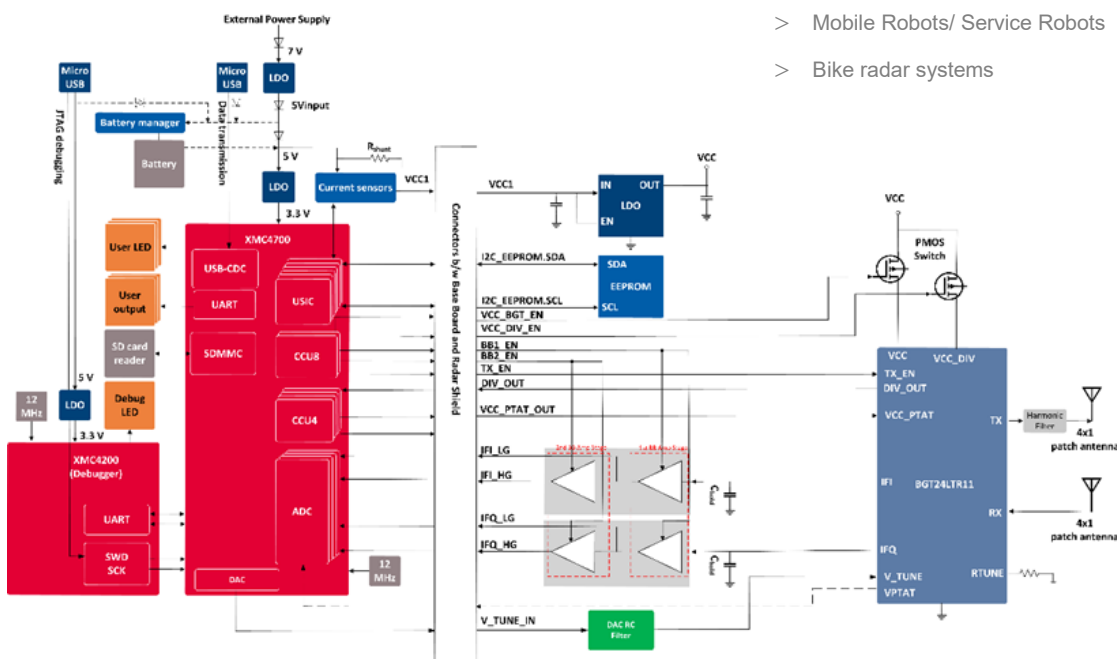
Competitive advantage

- > Low-power 24 GHz demo kit with smart 1D tracking algorithm
- > External hardware PLL is omitted which saves cost, power and PCB space

Target applications

- > Smart home devices incl. smart home appliances
- > Lighting systems (Indoor & Outdoor)
- > Unmanned Aerial Vehicles (UAV) such as drones
- > Security systems from commercial surveillance to low-power IP cameras
- > HVAC products like smart air conditioners
- > Smart sanitary facilities (e.g. smart toilets)
- > Mobile Robots/ Service Robots
- > Bike radar systems

Block diagram



Product collaterals /
Online support

[Product page](#)

[Product brief](#)

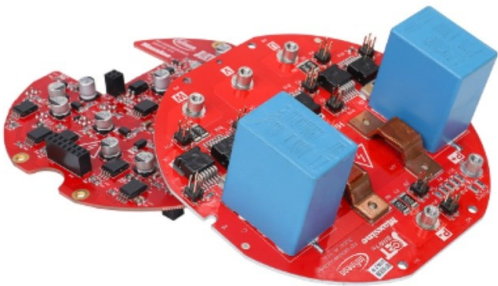
[Application note](#)

Product overview incl. datasheet and application note link

OPN	SP Number	Package
DEMODISTANCE2GOLTOBO1	SP005538336	Board

REF-DR3KIMBGSICMA

The SiC reference design REF-DR3KIMBGSICMA is the combination of an inverter board and a gate driver board for the demonstration of an integrated servo motor and drive. The driver circuit is based on EiceDriver™ IC - 1EDI20I12MH with Miller clamp function. CoolSiC™ MOSFET – IMBG120R45M1H is the main component for the 3-phase inverter.



To evaluate the electrical performance of the system, the iMOTION™ MADK EVAL-M1-101T can be used to provide a simple control.

Features

- > 1200 V, 45 mΩ CoolSiC™ MOSFET in SMD package (TO263-7L), with .XT interconnection technology
- > 3-phase servo motor with integrated drive
- > IMS (Insulated Metallic Substrate) PCBs with high thermal conductivity
- > Input voltage 350 – 800 VDC
- > Output voltage 220 VAC, 380 VAC, 480 VAC

Benefits

- > Possible for passive cooling without cooling fans
- > Ultra small footprint with a PCB diameter of 110 mm
- > High power density
- > Overcurrent protection

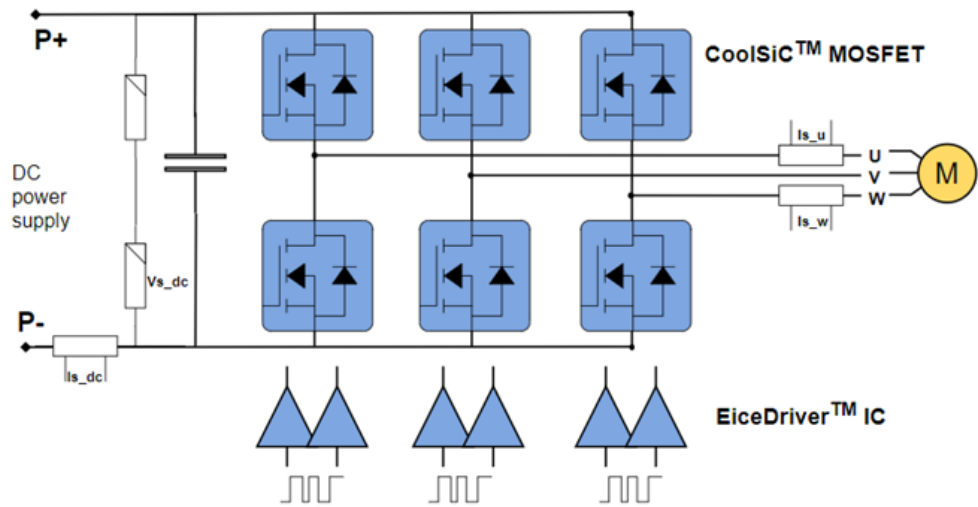
Target applications

- > Motor control and drives
- > Servo motor drive and control

Competitive advantage

- > A reference designs, which helps to design outdoor units (ODU) more efficient, denser and faster :
 - Efficiency - Excellent PFC performance with a power factor (PF) of 0.999 and a total harmonic distortion (THD) of 3.4% at 1.4 kW
 - Size - Up to 15% smaller design compared to discrete implementation
 - Speed - Reduced time to market by concentrating on application development rather than on motor control

Block diagram



Product collaterals /
Online support

[Product page](#)

[User manual](#)

Product overview incl. data sheet link

OPN	SP Number	Package
REFDR3KIMBGSICMATOBO1	SP005548242	Board

REF-AIRCON-C302-IM564

The reference design for motor control in residential aircon applications, REF-AIRCON-C302-IM564 is a 3-phase turnkey motor drive for air conditioner outdoor units (ODU) with an iMC302 iMOTION™ controller, a CIPOS™ Mini IPM IM564-X6D inverter with integrated PFC stage, a 1ED44175 gate driver for the PFC stage and a CoolSET™ ICE5AR4770BZS for the auxiliary supply.



Features

- > Typical 1400 W motor power with heatsink cooling
- > Maximum 2500 W motor power with forced convection
- > Input voltage range of 85...265 VAC incl. on-board auxiliary voltage supply
- > On-board inductor for 40~60 kHz PFC operation
- > Control interfaces to external BLDC or AC fan, 4-way valve and temperature sensor
- > Communication interface to indoor unit (IDU)
- > Overcurrent and over temperature protection and a fault diagnostic LED output
- > Small 2-layer PCB with 250 mm × 157 mm
- > Easy-to-use iMOTION™ control firmware

Benefits

- > Excellent PFC performance (power factor=0.999 and THD=3.4% measured for typical use case of 1400 W)
- > Up to 15% PCB space savings compared to discrete implementation
- > All interfaces for a complete system solution are on-board and can be controlled by Software
- > Ready-to-use motor control algorithms (incl. PFC) for high-efficiency permanent magnet synchronous motors (PMSM)

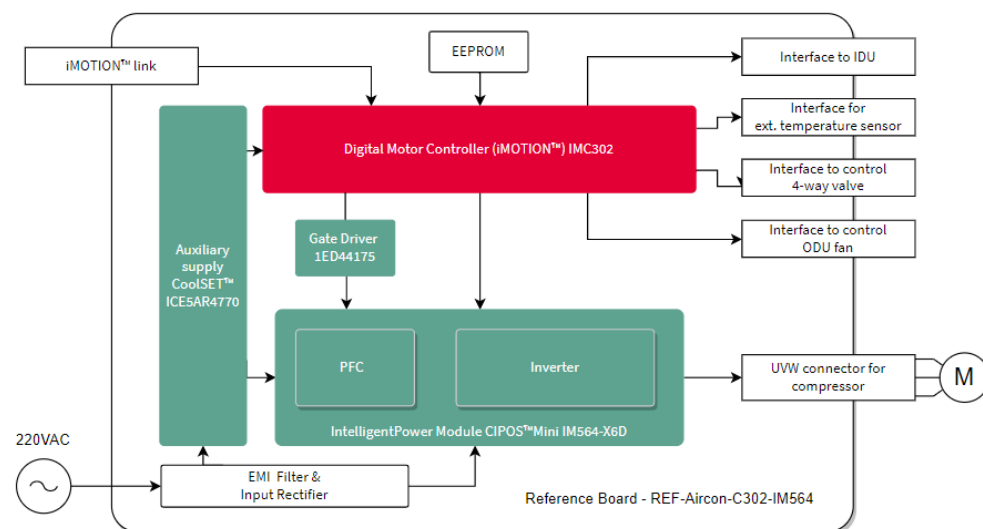
Competitive advantage

- > A reference designs, which helps to design outdoor units (ODU) more efficient, denser and faster :
- > Efficiency - Excellent PFC performance with a power factor (PF) of 0.999 and a total harmonic distortion (THD) of 3.4% at 1.4 kW
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- > Speed - Reduced time to market by concentrating on application development rather than on motor control

Target applications

- > Residential aircon - motor-, system control and monitoring

Block diagram



Product collaterals /
Online support

[Product page](#)

[User manual](#)

Product overview incl. data sheet link

OPN	SP Number	Package
REF-AIRCON-C302A-IM564	SP005561929	Board

Traveo™ II

Thanks to its special features the Traveo™ II family is the perfect match for connected-car. With processing power and network connectivity built into a single Arm® Cortex®- M4F and dual Cortex®- M7F, the Traveo™ II family comes up with an enhanced performance up to 1500 DMIPS and a high-performance CPU operating up to 350 MHz. Enhance lineup to add CYT4BF Series and CYT3BB/CYT4BB Series.



Features

- > HSM (Hardware security module)
- > eSHE (Enhanced Secure Hardware Extension)
- > Cortex®-M0+ for secure processing
- > Embedded flash in dual bank mode for FOTA requirements
- > Memory Protection Unit (MPU)

Benefits

- > Configurable HSM domains
- > Scalability to 8MB Flash and Cortex-M7 dual core
- > Read While Write dual bank operations
- > Low standby current with quick resume operation

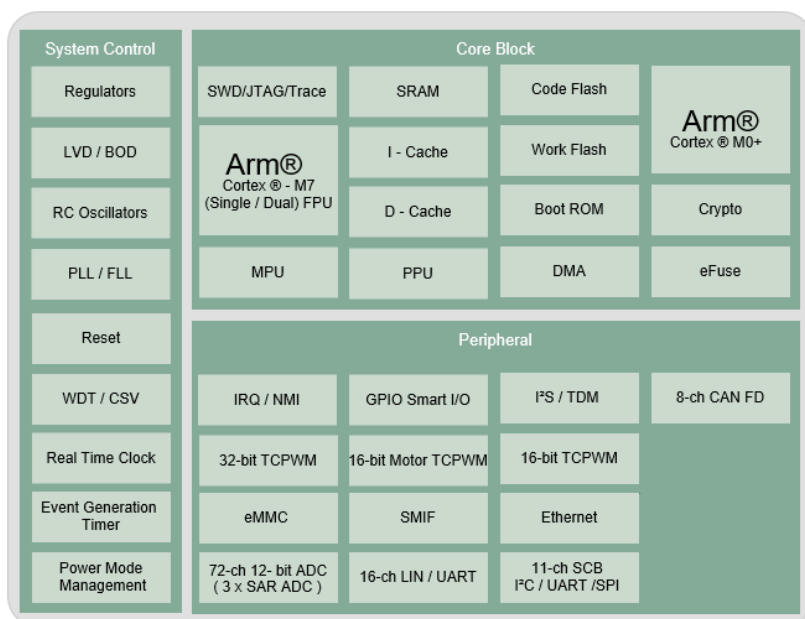
Target applications

- > Body application
- > Infotainment
- > Lighting
- > Cluster

Competitive advantage

- > Advantage on low power mode which fits perfectly to body applications for power consumption, security and safety solutions.

Block diagram Traveo™ II CYT3BB/CYT4BB Series



Product collaterals / Online support

[Product family page, CYT3BB/CYT4BB](#)

[Product family page, CYT4BF](#)

[Development tools](#)

[Application notes](#)

[Presentation](#)

Product overview incl. product page link

OPN	Package
CYT3BB8CEBQ0AESGS	TEQFP-176
CYT3BB8CEBQ0BZEGS	BGA-272
CYT4BF8CEDQ0AEEGS	TEQFP-176
CYT4BF8CEDQ0BZEGS	BGA-320



You can place the order for the launched Traveo™ II devices, through your standard Electronic Data Interchange (EDI) ordering process by entering the part number. If you do not have access to the standard ordering process, please get in contact with Wolfgang.Wiewesiek@infineon.com